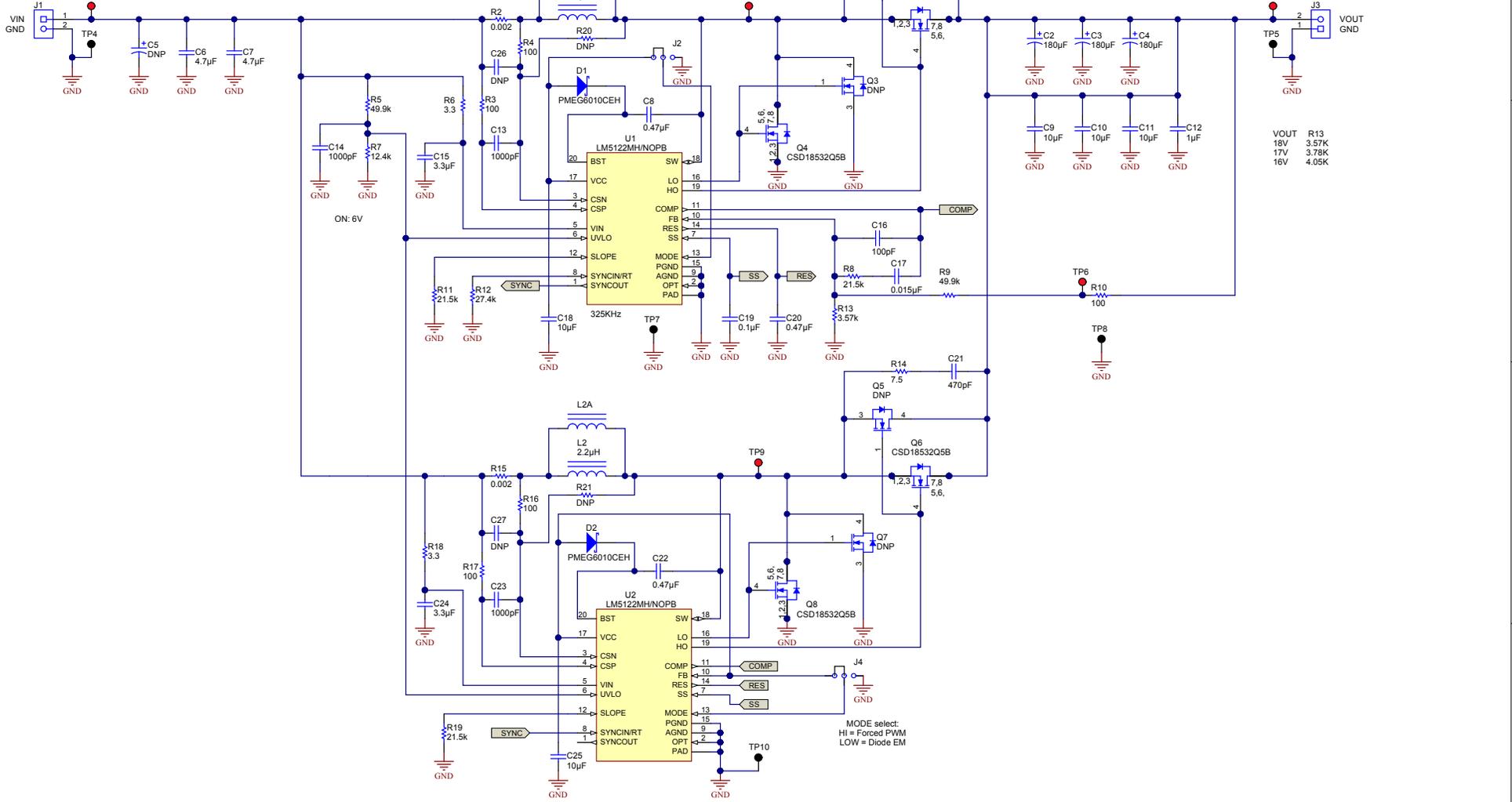


6V to 36Vin



NOTES:
 1) Sustained operation at low Vin will result in elevated operating temperatures.
 2) Input voltages over 18V will pass through to the output.

18V @ 15A

VOUT R13
 18V 3.57K
 17V 3.78K
 16V 4.05K

PCB
 LOGO
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Designed for: Public Release		Mod. Date: 4/2/2015	
Project Title: 2 Phase Sync Boost			
Number: PMP9595	Rev: B	Sheet Title:	
SVN Rev: Version control disabled		Assembly Variant: 001	Sheet: 1 of 1
Drawn By:	File: PMP9595 REV B SCH.SchDoc		Size: B
Engineer: J Betten	Contact: http://www.ti.com/support		http://www.ti.com
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